



Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

Model Name	HP Pavilion a1000 Series PC
Description	Desktop PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants	Declaration limited to case plastics only.	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0



Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Clipper	
Screw Driver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Panel Access Disassemble: loosening one thumb screw, removing panel-Access access
2	Front Bezel Disassemble: press and hold down, press tab(*4), take out front bezel
3	M/B Disassemble: turn the screws(*8) to loosen it , take M/B out of Chassis. <u>Remove RTC coin cell battery for selective treatment.</u>
4	EMI Shield Disassemble: pull snap up , take out of I/O shield
5	System Fan Disassemble: turn the screws(*4) to loosen it , take system fan out of Chassis
6	Power LED holder Disassemble: press Power LED holder hooks to take it out
7	Front I/O cover Disassemble: pull snap up(*4), pull the front I/O cover backward, take Front I/O bezel out of Front I/O bracket
8	Front I/O bracket Disassemble: turn the screw to loosen it, pull the front I/O bezel toward right, take Front I/O bracket out of chassis
9	Main Bezel Sub-Disassemble Optional parts: Press two hooks to take out of FDD bezel trim
10	ODD Disassemble : pull snap up ,take out ODD
11	HDD Disassemble : pull snap up ,take out HDD
12	Cardreader Disassemble : pull snap up ,take out Cardreader
13	Floppy Disassemble : pull snap up ,take out Floppy
14	Latch Disassemble: pull snap up , take out Latch
15	Power Supply Disassemble: turn the screws(*4) to loosen it , take Power Supply out of Chassis
16	Nameplate Disassemble: Ejecting two hooks



17	Power button Disassemble: press two hooks and take out the Power button
18	HDD lence Disassemble: press two hooks ,take out HDD lence
19	Cardreader bezel trim Disassemble: pull snap up , take out Cardreader bezel trim
20	Backup bezel Disassemble: pull hooks(*8) up, take out Backup bezel
21	<u>Eject ODD button*2</u> Disassemble: pull snap up, pull out Eject ODD button
22	<u>Spring of Eject ODD button*2</u> Disassemble: pull the spring out of the hooks
23	<u>CD shutter door*2</u> Disassemble: take off hinge(*2), takel out CD shutter door
24	<u>Basepan-CPU</u> Disassemble: take out the nail with driller ,and take out <u>Basepan-CPU</u>
25	<u>Bezel latch</u> Disassemble: take out <u>Bezel latch</u>

- 3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

